Cascade

SUMMIT200

200 mm Fully-automated Probe System

eVue™ IV Digital Imaging System
• Fast probe set-up with wide field-of-view and single objective in MicroChamber
• Easy navigation with multiple live video views of probes and wafer
• New high-speed focus system for faster and accurate die stepping
• New safety features for probes and usability

Versatile microscope mount
• High-stability or large-area
• Boom stand for low power optics
• Gross 2 HI with repeatable focus for easy access to probes
• Manual or programmable
• Field-upgradable

Connection panels
• Coaxial, triaxial, and pin jack feed troughs available
• Limit cable strain and motion for measurement stability
• Instrument stays connected to back of panel
• Probe connection made at front of panel
• Simple to re-arrange cabling when needed

Platen lift
• Easy and safe contact and separate function for probe cards and positioners
• Available micrometer adjustment to set probe card contact

TopHat™
• New TopHat covers for easier and higher-accuracy probe setup
• Allows full access to positioners and microscope at any temperature
• Allows probe adjustments without exposing wafer and chamber to external environment

PureLine™ technology
• Enhanced EMI shielding
• Lowest spectral noise floor and system AC noise
• Ideal for low-level and 1/f measurements

AttoGuard®
• Extends instrument guard to completely surround wafer
• Makes the station invisible to the instrument
• Extremely low capacitance and leakage characteristics
• Fast settling times

MicroChamber®
• EMI shielding for low-noise measurements
• Environmentally sealed for moisture-free, low-temperature measurements
• Low volume for the fastest purge
• Light tight to eliminate the need for a dark box

MicroChamber access door
• Auto-locking door to protect wafers at cold temperatures
• Full width for easy access to wafers and cal substrates
• Hardware interlock to prevent user from hazardous chuck bias voltage

Rollout stage
• Full wafer access for safe and easy loading
• Maintains chuck integrity without contaminating layers
• Easy access to calibration substrates on auxiliary chucks
• New Lift pin technology for fast manual load/unload of hot wafers

Velox™ probe station control software
• Innovative operating software for advanced probe operation, temperature control, 2-profiling and stepping
• Wafer mapping, automated wafer alignment, and auto XY and theta correction for sub-micron stepping

Velox™ PRO test automation software
• Easy-to-use SEMI E95 compliant user interface
• Efficient communication with test executive software
• Time saving test recipes

Automated wafer handling
• Up to 50 wafers with optional 2nd cassette
• Quick access port for maximum throughput
• Save time with parallel I/O reading and pipelining
• Fast load/unload wafer to hot/cold chuck (+60 °C to +300 °C)

Thin wafer testing
• Safe robot handling for thin/warped wafers down to 50 µm
• Advanced wafer handling for high-performance non-MicroVac Microchuck

Auxiliary chucks
• Up to 3 integrated multi-purpose mounts (calibration, cleaning, contact)
• New microwave absorber and material options (ceramic, steel)
• Thermally isolated to prevent load drift over temperature
• Automated probe cleaning capabilities

Chuck vacuum control
• Independent zones for various wafer sizes, dies and shards
• Easy access controls for auxiliary chucks

Modular chucks
• FemtoGuard® triaxial and coax versions available
• MicroVac™ option for thin wafer support and boost thermal conductivity
• High-performance thermal and economical non-thermal options
• Wide range of temperature options from -60 °C to 300 °C and higher

Manual mode stage control
• Intuitive manual chuck XY stage controls in semi-automatic engineering mode

Precision 200 mm wafer stage
• New user-selectable performance modes for standard, fast and high accuracy
• Increased test throughput with up to 100 mm/sec speed
• High reliability 24/7 operation

Contact Intelligence™ Technology
• Integrated HTS High Thermal Stability reduces probe drift and thermal soak time
• Optional VueTrack™ enables fast time to data even when measuring over a large thermal range
• Enables unattended test over multiple temperatures

Scalable system
• In-field upgradable wafer loading and automation
• Add test accuracy improvements for increased test performance

Compact small footprint
• Integrated vibration isolation for reliable small pad probing
• Integrated system electronics with power loss wafer safety protection

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